



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-03-05
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U535VET6Q	E31L*455XXXY	A	9991	2024-03-05
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	679	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	14x14	100	Gull wing	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	0			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E31L*455XXXY		678.7893		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	10.292	mg	supplier	die	Silicon (Si)	7440-21-3		9.896	mg	961581	14579				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	4261	65				
				supplier	metallization	Copper (Cu)	7440-50-8		0.130	mg	12646	192				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	69	1				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	2165	33				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	550	8				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	69	1				
				supplier	Passivation	Silicon Nitride	12033-89-6		0.031	mg	3024	46				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	15635	237				
				Leadframe (C7025)	Copper & its alloys	190.000	mg	supplier	Leadframe	Copper (Cu)	7440 - 50 - 8		179.360	mg	944000	264235
supplier	Leadframe	Silver (Ag)	7440 - 22 - 4						2.850	mg	15000	4199				
supplier	Leadframe	Magnesium (Mg)	7439 - 95 - 4						0.333	mg	1750	490				
supplier	Leadframe	Silicon (Si)	7440 - 21 - 3						1.378	mg	7250	2029				
supplier	Leadframe	Nickel (Ni)	7440 - 02 - 0						6.080	mg	32000	8957				
Glue epoxy (CRM-1076WA)	Precious metals	2.057	mg	supplier	Glue or tape	Silver Powder	7440-22-4		1.572	mg	764000	2316				
				supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.062	mg	30000	91				
				supplier	Glue or tape	Epoxy resin	Proprietary		0.123	mg	60000	182				
				supplier	Glue or tape	Hardener	Proprietary		0.062	mg	30000	91				
				supplier	Glue or tape	Ethylene dimethacrylate	97-90-5		0.154	mg	75000	227				
				supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.062	mg	30000	91				
				supplier	Glue or tape	Dicyandiamide	461-58-5		0.011	mg	5500	17				
				supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.011	mg	5500	17				
				Bonding wire (Au)	Precious metals	1.600	mg	supplier	Bonding wire	Gold	7440-57-5		1.582	mg	988500	2330
								supplier	Bonding wire	Palladium	7440-05-3		0.018	mg	11500	27
supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'-di	85954-11-6						18.158	mg	40000	26750				
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	453.940	mg	supplier	Molding Compound	Epoxy resin	Proprietary		9.079	mg	20000	13375				
				supplier	Molding Compound	Phenol Resin	Proprietary		34.046	mg	75000	50156				
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		322.070	mg	709500	474478				
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		68.091	mg	150000	100312				
				supplier	Molding Compound	Carbon black	1333-86-4		2.497	mg	5500	3678				
				supplier	Molding Compound											
External Plating	M-011 Other inorganic materials	20.900	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30787				
				#N/A	Matte Sn	Impurities	-		0.002	mg	100	3				